

Whole Chip ESD Protection

This Application IS a DIV of 10/205520

7/25/2002
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Background of the Invention

US Patent
6,730,968

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Field of the Invention

10 This invention relates to a whole chip electrostatic discharge, ESD, circuit and method.

In particular, this invention relates to distributing the circuit of this invention next to each input / output pad in order to provide parallel ESD current discharge paths.

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Description of Related Art

Figure 1 shows a prior art input/output protection circuit. This protection circuit is placed next to each input/output (I/O) pad. Each protection circuit, like the one shown in figure 1, is used to protect only one I/O pad. If one of the I/O pads is zapped with high voltage or high current, the electrostatic discharge, ESD, current 170 only flows through the protection circuit adjacent to the zapped I/O pad. The circuit in figure 1 is connected to the supply voltage Vcc 190 and to Vss 150 or ground. The circuit includes a p-channel metal oxide semiconductor field effect transistor PMOS FET device 110 and an n-channel metal oxide

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